

LOCTITE ABLESTIK 2025JR

December 2016

PRODUCT DESCRIPTION

LOCTITE ABLESTIK 2025JR provides the following product characteristics:

Technology	Proprietary Hybrid Chemistry		
Appearance	blue		
Cure	Heat cure		
Product Benefits	Non-conductive		
	Minimum bleed		
	High hot/wet die shear strengthGood adhesion to a variety of substrates		
	• 260°C reflow capability for Pb-free applications		
Application	Die attach		
Filler Type	Silica		
Typical Package Application	PBGA, FlexBGA and Stacking BGA		

LOCTITE ABLESTIK 2025JR adhesive is designed for die attach applications. This material is a suitable replacement for ABLEBOND 84-3MV adhesive.

TYPICAL PROPERTIES OF UNCURED MATERIAL

Thixotropic Index (0.5/5 rpm)	4.1
Viscosity, Brookfield CP51, 25 °C, mPa·s (cP):	
Speed 5 rpm	27,000
Work Life @ 25°C, hours	24
Shelf Life @ -40°C (from date of manufacture), days	365

TYPICAL CURING PERFORMANCE Cure Schedule

30 minute ramp to 150°C + 90 minutes @ 150°C

The above cure profiles are guideline recommendations. Cure conditions (time and temperature) may vary based on customers' experience and their application requirements, as well as customer curing equipment, oven loading and actual oven temperatures.

TYPICAL PROPERTIES OF CURED MATERIAL

Physical Properties:

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Coefficient of Thermal Expansion : Below Tg, ppm/°C Above Tg, ppm/°C		57 116
Glass Transition Temperature, Tan Δ Max,	°C	56
Tensile Modulus, DMTA:		
@ 25 °C		2,860 (414,807)
@ 150 °C	N/mm² (psi)	375 (54,389)
@ 200 °C	N/mm² (psi)	319 (46,267)
@ 250 °C	N/mm² (psi)	315 (45,686)
Extractable Ionic Content, ppm:		
Chloride (CI-)		<10
Sodium (Na+)		<10
Potassium (K+)		<10

TYPICAL PERFORMANCE OF CURED MATERIAL

Die Shear Strength:

2 X 2 mm Si die, kg-f/die,

Post Cure

Substrate	@25°C
Ag/Cu Leadframe	10.4
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GENERAL INFORMATION

For safe handling information on this product, consult the Safety Data Sheet, (SDS).

THAWING:

- 1. Allow container to reach room temperature before use.
- 2. After removing from the freezer, set the syringes to stand vertically while thawing.
- DO NOT open the container before contents reach 25°C temperature. Any moisture that collects on the thawed container should be removed prior to opening the container.
- DO NOT re-freeze. Once thawed to -40°C, the adhesive should not be re-frozen.



DIRECTIONS FOR USE

- Thawed material should immediately be placed on dispense equipment for use.
- If the adhesive is transferred to a final dispensing reservoir, care must be exercised to avoid entrapment of contaminants and/or air into the adhesive.
- Adhesive must be completely used within the product's recommended work life.
- Apply enough adhesive to achieve a 25 to 50 µm wet bondline thickness, dispensed with approximately 25 to 50 % filleting on all sides of the die.
- Alternate dispense amounts may be used depending on the application requirements.
- Star or crossed shaped dispense patterns will yield fewer bondline voids than the matrix style of dispense pattern.

Not for product specifications

The technical data contained herein are intended as reference only. Please contact your local quality department for assistance and recommendations on specifications for this product.

STORAGE:

Store product in the unopened container in a dry location. Storage information may be indicated on the product container labeling.

Optimal Storage: -40 °C. Storage below minus (-)40 °C or greater than minus (-)40 °C can adversely affect product properties.

Material removed from containers may be contaminated during use. Do not return product to the original container. Henkel Corporation cannot assume responsibility for product which has been contaminated or stored under conditions other than those previously indicated. If additional information is required, please contact your local Technical Service Center or Customer Service Representative.

Conversions

(°C x 1.8) + 32 = °F kV/mm x 25.4 = V/mil mm / 25.4 = inches N x 0.225 = lb N/mm x 5.71 = lb/in psi x 145 = N/mm² MPa = N/mm² N·m x 8.851 = lb·in N·m x 0.738 = lb·ft N·m x 0.142 = oz·in mPa·s = cP

Disclaimer

Note:

The information provided in this Technical Data Sheet (TDS) including the recommendations for use and application of the product are based on our knowledge and experience of the product as at the date of this TDS. The product can have a variety of different applications as well as differing application and working conditions in your environment that are beyond our control. Henkel is, therefore, not liable for the suitability of our product for the production processes and conditions in respect of which you use them, as well as the intended applications and results. We strongly recommend that you carry out your own prior trials to confirm such suitability of our product.

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Reference N/A